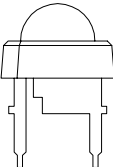


Features:

- Three dice - Single colour
- Water clear epoxy
- Low thermal resistance copper leadframe
- 4 leads with stand off
- Class II ESD Rating

Electro / Optical Characteristics $I_F = 20 \text{ mA}$ $T_a = 25^\circ \text{ C}$

Lamp Package	Part Number	Dice Qty	Emitting Colour	Epoxy Type	Die Material	Wavelength		Forward Voltage V_F	
						Peak λ_p	Dominant λ_d	typical	max
	FNL-P5DR078TWCCI	3	Red	WC	AlGaInP	632	624	2.00	2.40
	FNL-P5DO038TWCCI	3	Orange	WC	AlGaInP	611	604	2.00	2.40
	FNL-P5DY048TWCCI	3	Yellow	WC	AlGaInP	591	589	2.00	2.40
	FNL-P5DG16TWCCI	3	Green	WC	InGaN/SiC	518	527	3.85	4.00
	FNL-P5DG11TWCCI	3	Green	WC	InGaN/SiC	502	505	3.80	4.00
	FNL-P5DB11TWCCI	3	Blue	WC	InGaN/SiC	458	460	3.75	4.00
7.6 x 7.6 mm	Units					nm		VDC	

Intensity $T_a = 25^\circ \text{ C}$

Luminous intensity I_V		Viewing \angle 20 $\frac{1}{2}$
typical	@ I_F / Die	
3800	45	65
3500	45	65
3800	45	65
4100	30	65
3100	30	65
1000	30	65
mcd	mA	deg

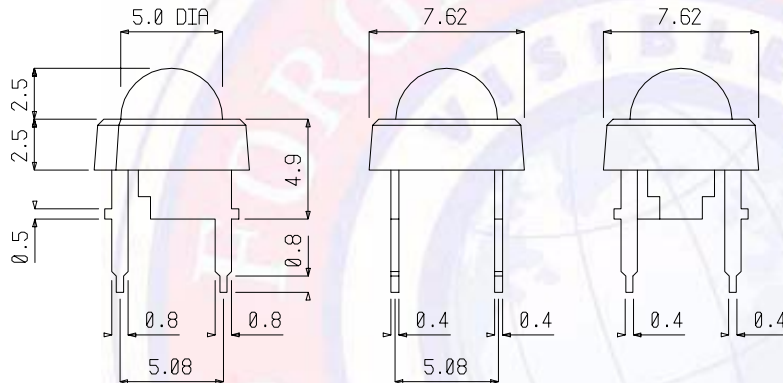
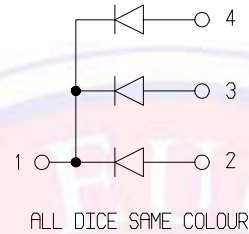
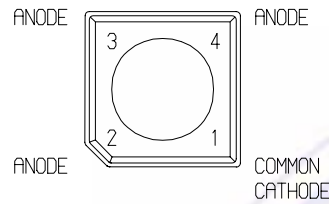
Note:

Intensity figures shown are with all dice powered

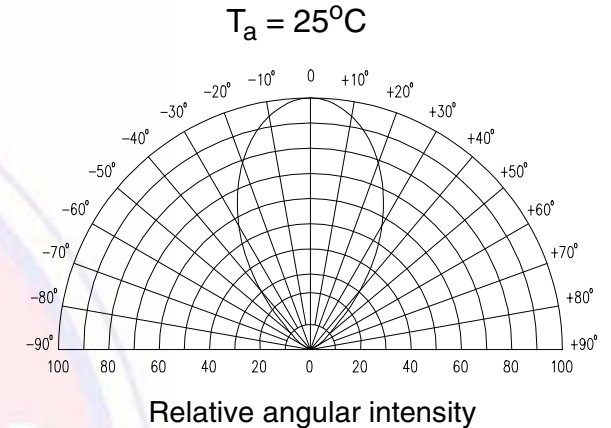
It is the responsibility of the customer to verify the suitability of the product for the application.

Package Outline

Dimensions in mm
Tol ± 0.25 mm
unless stated



Radiation Diagram



Note:

Due to manufacturing tolerances the maximum intensity position may deviate from the 0° point.

Maximum Ratings per die $T_a = 25^\circ\text{C}$ (Derate above 25° C)

Characteristic	Condition	Symbol	Rating / die
Pulse Forward Current	0.1 duty cycle @ 1KHz	I_{FP}	100
DC Forward Current		I_F	45
Reverse Voltage	$I_R = 10 \mu\text{A}$	V_R	10
Pulse Forward Current	0.1 duty cycle @ 1KHz	I_{FP}	100
DC Forward Current		I_F	30
Reverse Voltage	$I_R = 10 \mu\text{A}$	V_R	5
Operating Temperature		T_{opr}	- 20 to + 80
Storage Temperature		T_{stg}	- 20 to + 100
Lead soldering temperature	1.6 mm from body - max. 3 seconds		240

Note

Consideration must be given to forward current levels at elevated temperatures when driving all dice simultaneously to ensure maximum efficiency over the life of the product.

Industry standard procedures regarding static must be observed when handling product produced with the following die material.

InGaN/SiC